

Global MIP Package Substrates Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global MIP Package Substrates market size is expected to reach \$ 91.06 million by 2032, rising at a market growth of 25.8% CAGR during the forecast period (2026-2032).

In 2025, global MIP Package Substrates sales reached approximately 2,171 K Pcs with an average global market price of around 7.2 USD/Pcs.

MIP Package Substrates (Mini/Micro LED in Package Substrates) are high-density packaging substrates specifically designed for MIP chip-scale packaging technology. Centered on the core approach of 'package first, then assemble', this technology transfers micron-scale RGB LED chips—after sapphire substrate lift-off—onto package substrates via mass transfer, followed by encapsulation, singulation, testing, and optical mixing to form independent chip-scale packages, which are subsequently assembled into display modules. As the essential carrier of this technology, MIP package substrates provide multiple critical functions including mechanical support for chips, precision electrical interconnection, thermal dissipation management, and environmental protection. Notably, they adopt a fan-out package architecture that enlarges the fine-pitch pads of Micro LED chips to dimensions and spacings compatible with standard PCBs, thereby significantly reducing the manufacturing precision required for downstream circuit boards and substantially improving production yields and large-scale manufacturing efficiency. This design philosophy endows MIP technology with the unique advantage of compatibility with existing SMT production lines, offering a practical and scalable packaging pathway for transitioning Micro LED displays from laboratory settings to mass commercial applications.

MIP package substrates exhibit clear tiered gross margins across different product grades, with industry-wide gross margins typically ranging from 20% to 40%. Among

them, high-end FC-BGA-class substrates serving high-performance computing and AI acceleration scenarios often achieve margins above 30%, while mid-to-low-end products used in consumer-grade MIP displays command relatively lower margins. As MIP technology progressively enters large-scale production, unit costs are expected to decline significantly due to economies of scale and process maturation, thereby unlocking more attractive profitability for midstream substrate manufacturers. From an industrial chain perspective, upstream core materials primarily include ABF build-up films, BT resin substrates, and glass-based substrates. ABF films remain highly concentrated among a few overseas suppliers, representing the most critical bottleneck in the global MIP package substrate supply chain. The midstream segment is dominated by leading domestic IC substrate manufacturers, with capacity expansion and process upgrades advancing in parallel. Downstream, the chain directly serves LED packaging and display module manufacturers. The core value of MIP package substrates lies in their seamless compatibility with conventional SMT production lines, allowing downstream customers to adopt Micro LED technology without costly equipment overhauls—substantially lowering the barrier to industrialization and accelerating the commercial deployment of next-generation display technologies.

Market Development Opportunities & Main Driving Factors

The global MIP package substrate industry is entering a new phase of structural growth. From a fundamental demand perspective, the explosive expansion of AI computing infrastructure is reshaping the value distribution of the entire electronics supply chain. High-performance computing is increasingly dependent on advanced packaging technologies, and at the heart of advanced packaging lies the high-end substrate. In this context, IC substrates have evolved from passive components into strategic elements that determine chip-level system performance and delivery capability. Simultaneously, Micro LED display technology—recognized as the ultimate next-generation display solution—is transitioning from technical validation to large-scale commercialization. The MIP technology route, with its inherent compatibility with existing PCB production infrastructure, demonstrates significant advantages in cost control, mass-production adoption, and supply chain integration, and is widely regarded within the industry as one of the most viable pathways to overcoming the scalability challenges of Micro LED. As upstream chip efficiencies continue to improve and midstream packaging processes mature, MIP package substrates are poised to directly benefit from the synergistic growth of these two trillion-dollar markets, with demand accelerating from high-end commercial applications into mass-market segments including education, home displays, and automotive screens. For participants across the industrial chain, this represents not merely an opportunity for technological upgrading, but a strategic

window to reshape competitive landscapes.

Market Challenges, Risks & Restraints

Despite the promising outlook, the MIP package substrate industry faces multiple structural challenges. The most immediate risk stems from supply chain vulnerabilities in upstream critical materials. Global supply of core materials such as ABF build-up films remains highly concentrated among a few suppliers, leaving the industry with limited buffer capacity against geopolitical volatility or unforeseen disruptions. Moreover, the capacity expansion cycle for packaging substrates is substantially longer than that of standard PCBs, typically taking several years from planning to production release, resulting in severely constrained short-term supply elasticity. Current industry-wide utilization rates are already at elevated levels, and under a tight supply-demand equilibrium, any upside demand surprise could trigger bottlenecks. Additionally, the MIP technology route has not yet achieved full standardization, with production costs and yields still undergoing continuous optimization. Competitive pressure from alternative technologies such as COB is equally significant. Against the backdrop of persistent end-product pricing pressure, how to balance the capital intensity of capacity expansion with short-term profitability—while technologies are still maturing and customer adoption remains nascent—represents a core challenge that every industry participant must address.

Downstream Demand Trends

Structural upgrading of downstream demand is opening unprecedented growth opportunities for MIP package substrates. The most significant driver is the massive demand for high-performance computing capacity from AI data centers. The refresh cycle for infrastructure components such as servers, switches, and AI accelerators is accelerating, with each generation demanding higher layer counts, finer line/space geometries, and superior thermal performance from packaging substrates—directly driving both unit price and volume growth for high-end IC substrates. In parallel, the application boundaries of MIP technology in display markets continue to expand. From indoor ultra-high-definition large screens, virtual production studios, to high-end commercial displays, MIP package substrates have achieved full coverage of mainstream display pitch segments owing to their unique advantages in ultra-fine-pitch scenarios. More notably, as upstream chip costs trend downward and industrial chain synergies progressively materialize, MIP display solutions are penetrating from professional-grade markets into consumer-mass markets including home televisions and automotive displays. The simultaneous acceleration of multiple downstream

application domains implies that market demand for MIP package substrates is poised for non-linear growth. Companies that complete their technology accumulation and capacity deployment early stand to capture advantageous positions in this ongoing industrial transformation.

This report studies the global MIP Package Substrates production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for MIP Package Substrates and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of MIP Package Substrates that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global MIP Package Substrates total production and demand, 2021-2032, (K Pcs)

Global MIP Package Substrates total production value, 2021-2032, (USD Million)

Global MIP Package Substrates production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (K Pcs), (based on production site)

Global MIP Package Substrates consumption by region & country, CAGR, 2021-2032 & (K Pcs)

U.S. VS China: MIP Package Substrates domestic production, consumption, key domestic manufacturers and share

Global MIP Package Substrates production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (K Pcs)

Global MIP Package Substrates production by Type, production, value, CAGR, 2021-2032, (USD Million) & (K Pcs)

Global MIP Package Substrates production by Application, production, value, CAGR, 2021-2032, (USD Million) & (K Pcs)

This report profiles key players in the global MIP Package Substrates market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include WG-Tech, TGV TECH, Kyocera, UGPCB, HOREXS, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World MIP Package Substrates market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Pcs) and average price (US\$/Pcs) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global MIP Package Substrates Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global MIP Package Substrates Market, Segmentation by Type:

BT Substrates

Glass-based Substrates

Ceramic Substrates

Others

Global MIP Package Substrates Market, Segmentation by Packaged LED Device:

Micro LED MIP Substrates

Mini LED MIP Substrates

Hybrid MIP Substrates

Others

Global MIP Package Substrates Market, Segmentation by Package Structure:

Single-pixel MIP Substrates

Multi-in-one MIP Substrates

Others

Global MIP Package Substrates Market, Segmentation by Application:

Fine-pitch Direct-view LED Displays

Cinema and Premium Large-format Displays

Automotive Displays

AR/VR and Near-eye Displays

Others

Companies Profiled:

WG-Tech

TGV TECH

Kyocera

UGPCB

HOREXS

Key Questions Answered:

1. How big is the global MIP Package Substrates market?
2. What is the demand of the global MIP Package Substrates market?
3. What is the year over year growth of the global MIP Package Substrates market?
4. What is the production and production value of the global MIP Package Substrates market?
5. Who are the key producers in the global MIP Package Substrates market?
6. What are the growth factors driving the market demand?

Contents

1 SUPPLY SUMMARY

- 1.1 MIP Package Substrates Introduction
- 1.2 World MIP Package Substrates Supply & Forecast
 - 1.2.1 World MIP Package Substrates Production Value (2021 & 2025 & 2032)
 - 1.2.2 World MIP Package Substrates Production (2021-2032)
 - 1.2.3 World MIP Package Substrates Pricing Trends (2021-2032)
- 1.3 World MIP Package Substrates Production by Region (Based on Production Site)
 - 1.3.1 World MIP Package Substrates Production Value by Region (2021-2032)
 - 1.3.2 World MIP Package Substrates Production by Region (2021-2032)
 - 1.3.3 World MIP Package Substrates Average Price by Region (2021-2032)
 - 1.3.4 North America MIP Package Substrates Production (2021-2032)
 - 1.3.5 Europe MIP Package Substrates Production (2021-2032)
 - 1.3.6 China MIP Package Substrates Production (2021-2032)
 - 1.3.7 Japan MIP Package Substrates Production (2021-2032)
- 1.4 Market Drivers, Restraints and Trends
 - 1.4.1 MIP Package Substrates Market Drivers
 - 1.4.2 Factors Affecting Demand
 - 1.4.3 MIP Package Substrates Major Market Trends

2 DEMAND SUMMARY

- 2.1 World MIP Package Substrates Demand (2021-2032)
- 2.2 World MIP Package Substrates Consumption by Region
 - 2.2.1 World MIP Package Substrates Consumption by Region (2021-2026)
 - 2.2.2 World MIP Package Substrates Consumption Forecast by Region (2027-2032)
- 2.3 United States MIP Package Substrates Consumption (2021-2032)
- 2.4 China MIP Package Substrates Consumption (2021-2032)
- 2.5 Europe MIP Package Substrates Consumption (2021-2032)
- 2.6 Japan MIP Package Substrates Consumption (2021-2032)
- 2.7 South Korea MIP Package Substrates Consumption (2021-2032)
- 2.8 ASEAN MIP Package Substrates Consumption (2021-2032)
- 2.9 India MIP Package Substrates Consumption (2021-2032)

3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

- 3.1 World MIP Package Substrates Production Value by Manufacturer (2021-2026)

- 3.2 World MIP Package Substrates Production by Manufacturer (2021-2026)
- 3.3 World MIP Package Substrates Average Price by Manufacturer (2021-2026)
- 3.4 MIP Package Substrates Company Evaluation Quadrant
- 3.5 Industry Rank and Concentration Rate (CR)
 - 3.5.1 Global MIP Package Substrates Industry Rank of Major Manufacturers
 - 3.5.2 Global Concentration Ratios (CR4) for MIP Package Substrates in 2025
 - 3.5.3 Global Concentration Ratios (CR8) for MIP Package Substrates in 2025
- 3.6 MIP Package Substrates Market: Overall Company Footprint Analysis
 - 3.6.1 MIP Package Substrates Market: Region Footprint
 - 3.6.2 MIP Package Substrates Market: Company Product Type Footprint
 - 3.6.3 MIP Package Substrates Market: Company Product Application Footprint
- 3.7 Competitive Environment
 - 3.7.1 Historical Structure of the Industry
 - 3.7.2 Barriers of Market Entry
 - 3.7.3 Factors of Competition
- 3.8 New Entrant and Capacity Expansion Plans
- 3.9 Mergers, Acquisition, Agreements, and Collaborations

4 UNITED STATES VS CHINA VS REST OF THE WORLD

- 4.1 United States VS China: MIP Package Substrates Production Value Comparison
 - 4.1.1 United States VS China: MIP Package Substrates Production Value Comparison (2021 & 2025 & 2032)
 - 4.1.2 United States VS China: MIP Package Substrates Production Value Market Share Comparison (2021 & 2025 & 2032)
- 4.2 United States VS China: MIP Package Substrates Production Comparison
 - 4.2.1 United States VS China: MIP Package Substrates Production Comparison (2021 & 2025 & 2032)
 - 4.2.2 United States VS China: MIP Package Substrates Production Market Share Comparison (2021 & 2025 & 2032)
- 4.3 United States VS China: MIP Package Substrates Consumption Comparison
 - 4.3.1 United States VS China: MIP Package Substrates Consumption Comparison (2021 & 2025 & 2032)
 - 4.3.2 United States VS China: MIP Package Substrates Consumption Market Share Comparison (2021 & 2025 & 2032)
- 4.4 United States Based MIP Package Substrates Manufacturers and Market Share, 2021-2026
 - 4.4.1 United States Based MIP Package Substrates Manufacturers, Headquarters and Production Site (States, Country)

4.4.2 United States Based Manufacturers MIP Package Substrates Production Value (2021-2026)

4.4.3 United States Based Manufacturers MIP Package Substrates Production (2021-2026)

4.5 China Based MIP Package Substrates Manufacturers and Market Share

4.5.1 China Based MIP Package Substrates Manufacturers, Headquarters and Production Site (Province, Country)

4.5.2 China Based Manufacturers MIP Package Substrates Production Value (2021-2026)

4.5.3 China Based Manufacturers MIP Package Substrates Production (2021-2026)

4.6 Rest of World Based MIP Package Substrates Manufacturers and Market Share, 2021-2026

4.6.1 Rest of World Based MIP Package Substrates Manufacturers, Headquarters and Production Site (State, Country)

4.6.2 Rest of World Based Manufacturers MIP Package Substrates Production Value (2021-2026)

4.6.3 Rest of World Based Manufacturers MIP Package Substrates Production (2021-2026)

5 MARKET ANALYSIS BY TYPE

5.1 World MIP Package Substrates Market Size Overview by Type: 2021 VS 2025 VS 2032

5.2 Segment Introduction by Type

5.2.1 BT Substrates

5.2.2 Glass-based Substrates

5.2.3 Ceramic Substrates

5.2.4 Others

5.3 Market Segment by Type

5.3.1 World MIP Package Substrates Production by Type (2021-2032)

5.3.2 World MIP Package Substrates Production Value by Type (2021-2032)

5.3.3 World MIP Package Substrates Average Price by Type (2021-2032)

6 MARKET ANALYSIS BY PACKAGED LED DEVICE

6.1 World MIP Package Substrates Market Size Overview by Packaged LED Device: 2021 VS 2025 VS 2032

6.2 Segment Introduction by Packaged LED Device

6.2.1 Micro LED MIP Substrates

6.2.2 Mini LED MIP Substrates

6.2.3 Hybrid MIP Substrates

6.2.4 Others

6.3 Market Segment by Packaged LED Device

6.3.1 World MIP Package Substrates Production by Packaged LED Device
(2021-2032)

6.3.2 World MIP Package Substrates Production Value by Packaged LED Device
(2021-2032)

6.3.3 World MIP Package Substrates Average Price by Packaged LED Device
(2021-2032)

7 MARKET ANALYSIS BY PACKAGE STRUCTURE

7.1 World MIP Package Substrates Market Size Overview by Package Structure: 2021 VS 2025 VS 2032

7.2 Segment Introduction by Package Structure

7.2.1 Single-pixel MIP Substrates

7.2.2 Multi-in-one MIP Substrates

7.2.3 Others

7.3 Market Segment by Package Structure

7.3.1 World MIP Package Substrates Production by Package Structure (2021-2032)

7.3.2 World MIP Package Substrates Production Value by Package Structure
(2021-2032)

7.3.3 World MIP Package Substrates Average Price by Package Structure
(2021-2032)

8 MARKET ANALYSIS BY APPLICATION

8.1 World MIP Package Substrates Market Size Overview by Application: 2021 VS 2025 VS 2032

8.2 Segment Introduction by Application

8.2.1 Fine-pitch Direct-view LED Displays

8.2.2 Cinema and Premium Large-format Displays

8.2.3 Automotive Displays

8.2.4 AR/VR and Near-eye Displays

8.2.5 Others

8.3 Market Segment by Application

8.3.1 World MIP Package Substrates Production by Application (2021-2032)

8.3.2 World MIP Package Substrates Production Value by Application (2021-2032)

8.3.3 World MIP Package Substrates Average Price by Application (2021-2032)

9 COMPANY PROFILES

9.1 WG-Tech

9.1.1 WG-Tech Details

9.1.2 WG-Tech Major Business

9.1.3 WG-Tech MIP Package Substrates Product and Services

9.1.4 WG-Tech MIP Package Substrates Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.1.5 WG-Tech Recent Developments/Updates

9.1.6 WG-Tech Competitive Strengths & Weaknesses

9.2 TGV TECH

9.2.1 TGV TECH Details

9.2.2 TGV TECH Major Business

9.2.3 TGV TECH MIP Package Substrates Product and Services

9.2.4 TGV TECH MIP Package Substrates Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.2.5 TGV TECH Recent Developments/Updates

9.2.6 TGV TECH Competitive Strengths & Weaknesses

9.3 Kyocera

9.3.1 Kyocera Details

9.3.2 Kyocera Major Business

9.3.3 Kyocera MIP Package Substrates Product and Services

9.3.4 Kyocera MIP Package Substrates Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.3.5 Kyocera Recent Developments/Updates

9.3.6 Kyocera Competitive Strengths & Weaknesses

9.4 UGPCB

9.4.1 UGPCB Details

9.4.2 UGPCB Major Business

9.4.3 UGPCB MIP Package Substrates Product and Services

9.4.4 UGPCB MIP Package Substrates Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.4.5 UGPCB Recent Developments/Updates

9.4.6 UGPCB Competitive Strengths & Weaknesses

9.5 HOREXS

9.5.1 HOREXS Details

9.5.2 HOREXS Major Business

- 9.5.3 HOREXS MIP Package Substrates Product and Services
- 9.5.4 HOREXS MIP Package Substrates Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 9.5.5 HOREXS Recent Developments/Updates
- 9.5.6 HOREXS Competitive Strengths & Weaknesses

10 INDUSTRY CHAIN ANALYSIS

- 10.1 MIP Package Substrates Industry Chain
- 10.2 MIP Package Substrates Upstream Analysis
 - 10.2.1 MIP Package Substrates Core Raw Materials
 - 10.2.2 Main Manufacturers of MIP Package Substrates Core Raw Materials
- 10.3 Midstream Analysis
- 10.4 Downstream Analysis
- 10.5 MIP Package Substrates Production Mode
- 10.6 MIP Package Substrates Procurement Model
- 10.7 MIP Package Substrates Industry Sales Model and Sales Channels
 - 10.7.1 MIP Package Substrates Sales Model
 - 10.7.2 MIP Package Substrates Typical Distributors

11 RESEARCH FINDINGS AND CONCLUSION

12 APPENDIX

- 12.1 Methodology
- 12.2 Research Process and Data Source
- 12.3 Disclaimer

List Of Tables

LIST OF TABLES

Table 1. World MIP Package Substrates Production Value by Region (2021, 2025 and 2032) & (USD Million)

Table 2. World MIP Package Substrates Production Value by Region (2021-2026) & (USD Million)

Table 3. World MIP Package Substrates Production Value by Region (2027-2032) & (USD Million)

Table 4. World MIP Package Substrates Production Value Market Share by Region (2021-2026)

Table 5. World MIP Package Substrates Production Value Market Share by Region (2027-2032)

Table 6. World MIP Package Substrates Production by Region (2021-2026) & (K Pcs)

Table 7. World MIP Package Substrates Production by Region (2027-2032) & (K Pcs)

Table 8. World MIP Package Substrates Production Market Share by Region (2021-2026)

Table 9. World MIP Package Substrates Production Market Share by Region (2027-2032)

Table 10. World MIP Package Substrates Average Price by Region (2021-2026) & (US\$/Pcs)

Table 11. World MIP Package Substrates Average Price by Region (2027-2032) & (US\$/Pcs)

Table 12. MIP Package Substrates Major Market Trends

Table 13. World MIP Package Substrates Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (K Pcs)

Table 14. World MIP Package Substrates Consumption by Region (2021-2026) & (K Pcs)

Table 15. World MIP Package Substrates Consumption Forecast by Region (2027-2032) & (K Pcs)

Table 16. World MIP Package Substrates Production Value by Manufacturer (2021-2026) & (USD Million)

Table 17. Production Value Market Share of Key MIP Package Substrates Producers in 2025

Table 18. World MIP Package Substrates Production by Manufacturer (2021-2026) & (K Pcs)

Table 19. Production Market Share of Key MIP Package Substrates Producers in 2025

Table 20. World MIP Package Substrates Average Price by Manufacturer (2021-2026)

& (US\$/Pcs)

Table 21. Global MIP Package Substrates Company Evaluation Quadrant

Table 22. World MIP Package Substrates Industry Rank of Major Manufacturers, Based on Production Value in 2025

Table 23. Head Office and MIP Package Substrates Production Site of Key Manufacturer

Table 24. MIP Package Substrates Market: Company Product Type Footprint

Table 25. MIP Package Substrates Market: Company Product Application Footprint

Table 26. MIP Package Substrates Competitive Factors

Table 27. MIP Package Substrates New Entrant and Capacity Expansion Plans

Table 28. MIP Package Substrates Mergers & Acquisitions Activity

Table 29. United States VS China MIP Package Substrates Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)

Table 30. United States VS China MIP Package Substrates Production Comparison, (2021 & 2025 & 2032) & (K Pcs)

Table 31. United States VS China MIP Package Substrates Consumption Comparison, (2021 & 2025 & 2032) & (K Pcs)

Table 32. United States Based MIP Package Substrates Manufacturers, Headquarters and Production Site (States, Country)

Table 33. United States Based Manufacturers MIP Package Substrates Production Value, (2021-2026) & (USD Million)

Table 34. United States Based Manufacturers MIP Package Substrates Production Value Market Share (2021-2026)

Table 35. United States Based Manufacturers MIP Package Substrates Production (2021-2026) & (K Pcs)

Table 36. United States Based Manufacturers MIP Package Substrates Production Market Share (2021-2026)

Table 37. China Based MIP Package Substrates Manufacturers, Headquarters and Production Site (Province, Country)

Table 38. China Based Manufacturers MIP Package Substrates Production Value, (2021-2026) & (USD Million)

Table 39. China Based Manufacturers MIP Package Substrates Production Value Market Share (2021-2026)

Table 40. China Based Manufacturers MIP Package Substrates Production, (2021-2026) & (K Pcs)

Table 41. China Based Manufacturers MIP Package Substrates Production Market Share (2021-2026)

Table 42. Rest of World Based MIP Package Substrates Manufacturers, Headquarters and Production Site (State, Country)

Table 43. Rest of World Based Manufacturers MIP Package Substrates Production Value, (2021-2026) & (USD Million)

Table 44. Rest of World Based Manufacturers MIP Package Substrates Production Value Market Share (2021-2026)

Table 45. Rest of World Based Manufacturers MIP Package Substrates Production, (2021-2026) & (K Pcs)

Table 46. Rest of World Based Manufacturers MIP Package Substrates Production Market Share (2021-2026)

Table 47. World MIP Package Substrates Production Value by Type, (USD Million), 2021 & 2025 & 2032

Table 48. World MIP Package Substrates Production by Type (2021-2026) & (K Pcs)

Table 49. World MIP Package Substrates Production by Type (2027-2032) & (K Pcs)

Table 50. World MIP Package Substrates Production Value by Type (2021-2026) & (USD Million)

Table 51. World MIP Package Substrates Production Value by Type (2027-2032) & (USD Million)

Table 52. World MIP Package Substrates Average Price by Type (2021-2026) & (US\$/Pcs)

Table 53. World MIP Package Substrates Average Price by Type (2027-2032) & (US\$/Pcs)

Table 54. World MIP Package Substrates Production Value by Packaged LED Device, (USD Million), 2021 & 2025 & 2032

Table 55. World MIP Package Substrates Production by Packaged LED Device (2021-2026) & (K Pcs)

Table 56. World MIP Package Substrates Production by Packaged LED Device (2027-2032) & (K Pcs)

Table 57. World MIP Package Substrates Production Value by Packaged LED Device (2021-2026) & (USD Million)

Table 58. World MIP Package Substrates Production Value by Packaged LED Device (2027-2032) & (USD Million)

Table 59. World MIP Package Substrates Average Price by Packaged LED Device (2021-2026) & (US\$/Pcs)

Table 60. World MIP Package Substrates Average Price by Packaged LED Device (2027-2032) & (US\$/Pcs)

Table 61. World MIP Package Substrates Production Value by Package Structure, (USD Million), 2021 & 2025 & 2032

Table 62. World MIP Package Substrates Production by Package Structure (2021-2026) & (K Pcs)

Table 63. World MIP Package Substrates Production by Package Structure (2027-2032)

& (K Pcs)

Table 64. World MIP Package Substrates Production Value by Package Structure (2021-2026) & (USD Million)

Table 65. World MIP Package Substrates Production Value by Package Structure (2027-2032) & (USD Million)

Table 66. World MIP Package Substrates Average Price by Package Structure (2021-2026) & (US\$/Pcs)

Table 67. World MIP Package Substrates Average Price by Package Structure (2027-2032) & (US\$/Pcs)

Table 68. World MIP Package Substrates Production Value by Application, (USD Million), 2021 & 2025 & 2032

Table 69. World MIP Package Substrates Production by Application (2021-2026) & (K Pcs)

Table 70. World MIP Package Substrates Production by Application (2027-2032) & (K Pcs)

Table 71. World MIP Package Substrates Production Value by Application (2021-2026) & (USD Million)

Table 72. World MIP Package Substrates Production Value by Application (2027-2032) & (USD Million)

Table 73. World MIP Package Substrates Average Price by Application (2021-2026) & (US\$/Pcs)

Table 74. World MIP Package Substrates Average Price by Application (2027-2032) & (US\$/Pcs)

Table 75. WG-Tech Basic Information, Manufacturing Base and Competitors

Table 76. WG-Tech Major Business

Table 77. WG-Tech MIP Package Substrates Product and Services

Table 78. WG-Tech MIP Package Substrates Production (K Pcs), Price (US\$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 79. WG-Tech Recent Developments/Updates

Table 80. WG-Tech Competitive Strengths & Weaknesses

Table 81. TGV TECH Basic Information, Manufacturing Base and Competitors

Table 82. TGV TECH Major Business

Table 83. TGV TECH MIP Package Substrates Product and Services

Table 84. TGV TECH MIP Package Substrates Production (K Pcs), Price (US\$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 85. TGV TECH Recent Developments/Updates

Table 86. TGV TECH Competitive Strengths & Weaknesses

Table 87. Kyocera Basic Information, Manufacturing Base and Competitors

Table 88. Kyocera Major Business

- Table 89. Kyocera MIP Package Substrates Product and Services
- Table 90. Kyocera MIP Package Substrates Production (K Pcs), Price (US\$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 91. Kyocera Recent Developments/Updates
- Table 92. Kyocera Competitive Strengths & Weaknesses
- Table 93. UGPCB Basic Information, Manufacturing Base and Competitors
- Table 94. UGPCB Major Business
- Table 95. UGPCB MIP Package Substrates Product and Services
- Table 96. UGPCB MIP Package Substrates Production (K Pcs), Price (US\$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 97. UGPCB Recent Developments/Updates
- Table 98. UGPCB Competitive Strengths & Weaknesses
- Table 99. HOREXS Basic Information, Manufacturing Base and Competitors
- Table 100. HOREXS Major Business
- Table 101. HOREXS MIP Package Substrates Product and Services
- Table 102. HOREXS MIP Package Substrates Production (K Pcs), Price (US\$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
- Table 103. HOREXS Recent Developments/Updates
- Table 104. HOREXS Competitive Strengths & Weaknesses
- Table 105. Global Key Players of MIP Package Substrates Upstream (Raw Materials)
- Table 106. Global MIP Package Substrates Typical Customers
- Table 107. MIP Package Substrates Typical Distributors

List Of Figures

LIST OF FIGURES

- Figure 1. MIP Package Substrates Picture
- Figure 2. World MIP Package Substrates Production Value: 2021 & 2025 & 2032, (USD Million)
- Figure 3. World MIP Package Substrates Production Value and Forecast (2021-2032) & (USD Million)
- Figure 4. World MIP Package Substrates Production (2021-2032) & (K Pcs)
- Figure 5. World MIP Package Substrates Average Price (2021-2032) & (US\$/Pcs)
- Figure 6. World MIP Package Substrates Production Value Market Share by Region (2021-2032)
- Figure 7. World MIP Package Substrates Production Market Share by Region (2021-2032)
- Figure 8. North America MIP Package Substrates Production (2021-2032) & (K Pcs)
- Figure 9. Europe MIP Package Substrates Production (2021-2032) & (K Pcs)
- Figure 10. China MIP Package Substrates Production (2021-2032) & (K Pcs)
- Figure 11. Japan MIP Package Substrates Production (2021-2032) & (K Pcs)
- Figure 12. MIP Package Substrates Market Drivers
- Figure 13. Factors Affecting Demand
- Figure 14. World MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 15. World MIP Package Substrates Consumption Market Share by Region (2021-2032)
- Figure 16. United States MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 17. China MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 18. Europe MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 19. Japan MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 20. South Korea MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 21. ASEAN MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 22. India MIP Package Substrates Consumption (2021-2032) & (K Pcs)
- Figure 23. Producer Shipments of MIP Package Substrates by Manufacturer Revenue (\$MM) and Market Share (%): 2025
- Figure 24. Global Four-firm Concentration Ratios (CR4) for MIP Package Substrates Markets in 2025
- Figure 25. Global Four-firm Concentration Ratios (CR8) for MIP Package Substrates Markets in 2025
- Figure 26. United States VS China: MIP Package Substrates Production Value Market Share Comparison (2021 & 2025 & 2032)

Figure 27. United States VS China: MIP Package Substrates Production Market Share Comparison (2021 & 2025 & 2032)

Figure 28. United States VS China: MIP Package Substrates Consumption Market Share Comparison (2021 & 2025 & 2032)

Figure 29. United States Based Manufacturers MIP Package Substrates Production Market Share 2025

Figure 30. China Based Manufacturers MIP Package Substrates Production Market Share 2025

Figure 31. Rest of World Based Manufacturers MIP Package Substrates Production Market Share 2025

Figure 32. World MIP Package Substrates Production Value by Type, (USD Million), 2021 & 2025 & 2032

Figure 33. World MIP Package Substrates Production Value Market Share by Type in 2025

Figure 34. BT Substrates

Figure 35. Glass-based Substrates

Figure 36. Ceramic Substrates

Figure 37. Others

Figure 38. World MIP Package Substrates Production Market Share by Type (2021-2032)

Figure 39. World MIP Package Substrates Production Value Market Share by Type (2021-2032)

Figure 40. World MIP Package Substrates Average Price by Type (2021-2032) & (US\$/Pcs)

Figure 41. World MIP Package Substrates Production Value by Packaged LED Device, (USD Million), 2021 & 2025 & 2032

Figure 42. World MIP Package Substrates Production Value Market Share by Packaged LED Device in 2025

Figure 43. Micro LED MIP Substrates

Figure 44. Mini LED MIP Substrates

Figure 45. Hybrid MIP Substrates

Figure 46. Others

Figure 47. World MIP Package Substrates Production Market Share by Packaged LED Device (2021-2032)

Figure 48. World MIP Package Substrates Production Value Market Share by Packaged LED Device (2021-2032)

Figure 49. World MIP Package Substrates Average Price by Packaged LED Device (2021-2032) & (US\$/Pcs)

Figure 50. World MIP Package Substrates Production Value by Package Structure,

(USD Million), 2021 & 2025 & 2032

Figure 51. World MIP Package Substrates Production Value Market Share by Package Structure in 2025

Figure 52. Single-pixel MIP Substrates

Figure 53. Multi-in-one MIP Substrates

Figure 54. Others

Figure 55. World MIP Package Substrates Production Market Share by Package Structure (2021-2032)

Figure 56. World MIP Package Substrates Production Value Market Share by Package Structure (2021-2032)

Figure 57. World MIP Package Substrates Average Price by Package Structure (2021-2032) & (US\$/Pcs)

Figure 58. World MIP Package Substrates Production Value by Application, (USD Million), 2021 & 2025 & 2032

Figure 59. World MIP Package Substrates Production Value Market Share by Application in 2025

Figure 60. Fine-pitch Direct-view LED Displays

Figure 61. Cinema and Premium Large-format Displays

Figure 62. Automotive Displays

Figure 63. AR/VR and Near-eye Displays

Figure 64. Others

Figure 65. World MIP Package Substrates Production Market Share by Application (2021-2032)

Figure 66. World MIP Package Substrates Production Value Market Share by Application (2021-2032)

Figure 67. World MIP Package Substrates Average Price by Application (2021-2032) & (US\$/Pcs)

Figure 68. MIP Package Substrates Industry Chain

Figure 69. MIP Package Substrates Procurement Model

Figure 70. MIP Package Substrates Sales Model

Figure 71. MIP Package Substrates Sales Channels, Direct Sales, and Distribution

Figure 72. Methodology

Figure 73. Research Process and Data Source

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